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In re application of: Sung-Fei WANG, et al

Serial No.: 10/087,432

Group No.: 2827

Filed: March 1, 2002

Examiner: J. Mitchell

For: STACKED SEMICONDUCTOR CHIP PACKAGE

Attorney Docket No.: U-013887-9

Commissioner Patents and Trademarks
Washington, DC 20231

RESPONSE TO ACTION OF JUNE 6, 2002

Sir:

Please amend the above application as follows.

IN THE CLAIMS:

5. (amended) A stacked semiconductor chip package comprising:

CERTIFICATE OF MAILING (37 CFR 1.8a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Commissioner of Patents and Trademarks, Washington, DC 20231

WILLIAM R. EVANS

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Date: September 5, 2002

(Signature of person mailing paper)